WHAT IS CLAIMED IS:

1. A method for producing an organic electroluminescent device by using a transfer material comprising at least one organic layer formed on a support, comprising the steps of superposing said transfer material on a first substrate having an electrode formed at least partially thereon such that said organic layer of said transfer material faces said electrode on said first substrate; applying heat and/or pressure thereto to form a laminate; and peeling said support from said laminate so that said organic layer is transferred onto said first substrate via said electrode, wherein said first substrate has a maximum surface roughness Rmax of 0 to 50 according to JIS B 0601-1982, assuming that the thickness of said organic layer is 100.

2. The method of claim 1, wherein after the transfer of said organic layer onto said first substrate via said electrode, a second substrate having an electrode formed at least partially thereon is laminated to said organic layer on said first substrate.

3. The method of claim 2, wherein a surface of said second substrate, on which said electrode is formed, has a maximum surface roughness Rmax of 0 to 50 according to JIS B 0601-1982, assuming that the thickness of said organic layer is 100.

4. The method of claim 2, wherein at least one of said first and second substrates has a linear thermal expansion coefficient of 20 ppm/°C or less.

5. The method of claim 2, wherein a flat layer is formed on at least one of said first and second substrates.

6. The method of claim 5, wherein said flat layer is made of at least one material selected form the group consisting of ultraviolet-curing organic compounds, electron beam-curing organic compounds, thermosetting organic compounds, inorganic oxides and inorganic nitrides.

7. A method for producing an organic electroluminescent device by

using a transfer material comprising at least one organic layer formed on a plate having a pattern, comprising the steps of superposing said transfer material on a first substrate having an electrode formed at least partially thereon such that said organic layer of said transfer material faces said electrode on said first substrate; applying heat and/or pressure thereto to form a laminate; and peeling said plate form said laminate so that said organic layer is transferred onto said first substrate via said electrode, wherein said first substrate has a maximum surface roughness Rmax of 0 to 50 according to JIS B 0601-1982, assuming that the thickness of said organic layer is 100.

8. The method of claim 7, wherein after the transfer of said organic layer onto said first substrate via said electrode, a second substrate having an electrode formed at least partially thereon is laminated to said organic layer on said first substrate.

9. The method of claim 8, wherein a surface of said second substrate, on which said electrode is formed, has a maximum surface roughness Rmax of 0 to 50 according to JIS B 0601-1982, assuming that the thickness of said organic layer is 100.

10. The method of claim 8, wherein at least one of said first and second substrates has a linear thermal expansion coefficient of 20 ppm/°C or less.

11. The method of claim 8, wherein a flat layer is formed on at least one of said first and second substrates.

12. The method of claim 11, wherein said flat layer is made of at least one material selected form the group consisting of ultraviolet-curing organic compounds, electron beam-curing organic compounds, thermosetting organic compounds, inorganic oxides and inorganic nitrides.

13. An organic electroluminescent device produced by a method comprising the steps of superposing a transfer material comprising at least

one organic layer formed on a support on a first substrate having an electrode formed at least partially thereon such that said organic layer of said transfer material faces said electrode on said first substrate; applying heat and/or pressure thereto to form a laminate; and peeling said support from said laminate so that said organic layer is transferred onto said first substrate via said electrode, wherein said first substrate has a maximum surface roughness Rmax of 0 to 50 according to JIS B 0601-1982, assuming that the thickness of said organic layer is 100.

14. The device of claim 13, wherein after the transfer of said organic layer onto said first substrate via said electrode, a second substrate having an electrode formed at least partially thereon is laminated to said organic layer on said first substrate.

15. The device of claim 14, wherein a surface of said second substrate, on which said electrode is formed, has a maximum surface roughness Rmax of 0 to 50 according to JIS B 0601-1982, assuming that the thickness of said organic layer is 100.

16. The device of claim 14, wherein at least one of said first and second substrates has a linear thermal expansion coefficient of 20 ppm/°C or less.

17. The device of claim 14, wherein a flat layer is formed on at least one of said first and second substrates.

18. The device of claim 17, wherein said flat layer is made of at least one material selected form the group consisting of ultraviolet-curing organic compounds, electron beam-curing organic compounds, thermosetting organic compounds, inorganic oxides and inorganic nitrides.

19. An organic electroluminescent device produced by a method comprising the steps of superposing a transfer material comprising at least one organic layer formed on a plate having a pattern on a first substrate having an electrode formed at least partially thereon such that said organic

layer of said transfer material faces said electrode on said first substrate; applying heat and/or pressure thereto to form a laminate; and peeling said plate form said laminate so that said organic layer is transferred onto said first substrate via said electrode, wherein said first substrate has a maximum surface roughness Rmax of 0 to 50 according to JIS B 0601-1982, assuming that the thickness of said organic layer is 100.

20. The device of claim 19, wherein after the transfer of said organic layer onto said first substrate via said electrode, a second substrate having an electrode formed at least partially thereon is laminated to said organic layer on said first substrate.

21. The device of claim 20, wherein a surface of said second substrate, on which said electrode is formed, has a maximum surface roughness Rmax of 0 to 50 according to JIS B 0601-1982, assuming that the thickness of said organic layer is 100.

22. The device of claim 20, wherein at least one of said first and second substrates has a linear thermal expansion coefficient of 20 ppm/°C or less.

23. The device of claim 20, wherein a flat layer is formed on at least one of said first and second substrates.

24. The device of claim 23, wherein said flat layer is made of at least one material selected form the group consisting of ultraviolet-curing organic compounds, electron beam-curing organic compounds, thermosetting organic compounds, inorganic oxides and inorganic nitrides.